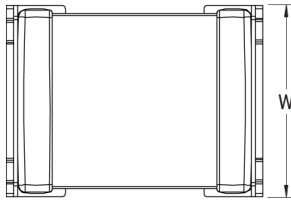
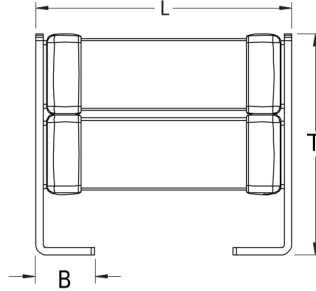


TOP VIEW
Single or Double Chip Stack



SIDE VIEW
Double Chip Stack



Click [here](#) for the 3D model.

Dimensions

L	3.5mm +/-0.3mm
W	2.6mm +/-0.3mm
T	6.15mm +/-0.15mm
B	0.8mm +/-0.15mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	300

General Information

Series	KPS SMD Comm X8L HT150C
Style	Stacked Chip
Description	SMD, MLCC, Stacked, Double Chip, High Temperature
Features	High Temperature
RoHS	Yes
Termination	Tin
AEC-Q200	No
Typical Component Weight	290 mg
Chip Size	1210-2
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	3.3 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	20%
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	X8L
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	+15% (-55C to +125C), +15/-40% (125C to 150C), 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	151.5 MOhms

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